# NCE N-Channel Enhancement Mode Power MOSFET

### **Description**

The NCE2006Y uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

V<sub>DS</sub> =20V,I<sub>D</sub> =6A

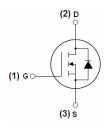
 $R_{DS(ON)}$  <13m $\Omega$  @  $V_{GS}$ =4.5V (Typ:10.5m $\Omega$ )

 $R_{DS(ON)}$  <18m $\Omega$  @  $V_{GS}$ =2.5V (Typ:15m $\Omega$ )

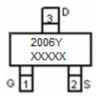
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

# **Application**

- Power switching application
- Load switching
- Uninterruptible power supply



### Schematic diagram



#### Marking and pin Assignment



SOT-23-3L top view

#### Package Marking and Ordering Information

|                       | <u> </u> |                |           |            |            |
|-----------------------|----------|----------------|-----------|------------|------------|
| <b>Device Marking</b> | Device   | Device Package | Reel Size | Tape width | Quantity   |
| 2006Y                 | NCE2006Y | SOT23-3L       | Ø180mm    | 8mm        | 3000 units |

Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

| Parameter  | Symbol                | Limit      | Unit |
|--|-----------------------|------------|------|
| Drain-Source Voltage                             | V <sub>DS</sub>       | 20         | V    |
| Gate-Source Voltage                              | V <sub>GS</sub>       | ±12        | V    |
| Drain Current-Continuous                         | I <sub>D</sub>        | 6          | Α    |
| Drain Current-Continuous(T <sub>C</sub> =100℃)   | I <sub>D</sub> (100℃) | 4.2        | Α    |
| Pulsed Drain Current                             | I <sub>DM</sub>       | 24         | Α    |
| Maximum Power Dissipation                        | P <sub>D</sub>        | 1.5        | W    |
| Operating Junction and Storage Temperature Range | $T_{J}, T_{STG}$      | -55 To 150 | °C   |

## Thermal Characteristic

| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 83.3 | °C/W |
|--|-----------------|------|------|
|--|-----------------|------|------|

## **Electrical Characteristics (T<sub>A</sub>=25 ℃ unless otherwise noted)**

| Parameter                      | Symbol            | Condition                                 | Min | Тур | Max | Unit |
|--------------------------------|-------------------|---|-----|-----|-----|------|
| Off Characteristics            |                   |   |     |     |     |      |
| Drain-Source Breakdown Voltage | BV <sub>DSS</sub> | V <sub>GS</sub> =0V I <sub>D</sub> =250μA | 20  | -   | -   | V    |

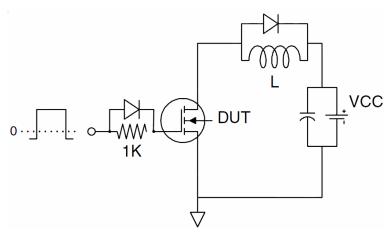
| Parameter                          | Symbol              | Condition  | Min      | Тур  | Max  | Unit |  |
|------------------------------------|---------------------|--|----------|------|------|------|--|
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>    | V <sub>DS</sub> =20V,V <sub>GS</sub> =0V                     | -        | -    | 1    | μA   |  |
| Gate-Body Leakage Current          | I <sub>GSS</sub>    | V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V                    | -        | -    | ±100 | nA   |  |
| On Characteristics (Note 3)        | •                   |  | •        |      |      |      |  |
| Gate Threshold Voltage             | $V_{GS(th)}$        | $V_{DS}=V_{GS}$ , $I_{D}=250\mu A$                           | 0.5      | 0.7  | 1.2  | V    |  |
| Daile Communication Constitution   | -                   | V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A                    | -        | 10.5 | 13   |      |  |
| Drain-Source On-State Resistance   | R <sub>DS(ON)</sub> | V <sub>GS</sub> =2.5V, I <sub>D</sub> =5A                    |          | 15   | 18   | mΩ   |  |
| Dynamic Characteristics (Note4)    | 1                   | 1  | <b>I</b> |      |      | I    |  |
| Input Capacitance                  | C <sub>lss</sub>    | .,   |          | 620  |      | PF   |  |
| Output Capacitance                 | C <sub>oss</sub>    | V <sub>DS</sub> =10V,V <sub>GS</sub> =0V,                    |          | 125  |      | PF   |  |
| Reverse Transfer Capacitance       | C <sub>rss</sub>    | F=1.0MHz   |          | 64   |      | PF   |  |
| Switching Characteristics (Note 4) | 1                   | 1  | <b>I</b> |      |      | I    |  |
| Turn-on Delay Time                 | $t_{d(on)}$         |  | -        | 4.5  | -    | nS   |  |
| Turn-on Rise Time                  | t <sub>r</sub>      | V <sub>GS</sub> =10V,V <sub>DS</sub> =10V                    | -        | 9.2  | -    | nS   |  |
| Turn-Off Delay Time                | $t_{d(off)}$        | $R_L$ =0. $5\Omega$ , $R_G$ = $3\Omega$                      | -        | 18.7 | -    | nS   |  |
| Turn-Off Fall Time                 | t <sub>f</sub>      |  | -        | 3.3  | -    | nS   |  |
| Total Gate Charge                  | Qg                  |  |          | 15   |      | nC   |  |
| Gate-Source Charge                 | Q <sub>gs</sub>     | V <sub>GS</sub> =10V,V <sub>DS</sub> =10V,I <sub>D</sub> =6A |          | 1.8  |      | nC   |  |
| Gate-Drain Charge                  | $Q_gd$              |  |          | 2.8  |      | nC   |  |
| Drain-Source Diode Characteristics | I                   | 1  |          | 1    |      | ı    |  |
| Diode Forward Voltage (Note 3)     | V <sub>SD</sub>     | V <sub>GS</sub> =0V,I <sub>S</sub> =6A                       | -        | -    | 1.2  | V    |  |
| Diode Forward Current (Note 2)     | Is                  | -  | _        | -    | 6    | Α    |  |

### Notes:

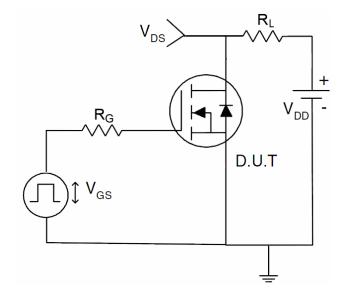
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- Surface Mounted on FR4 Board, t ≤ 10 sec.
  Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production

## **Test circuit**

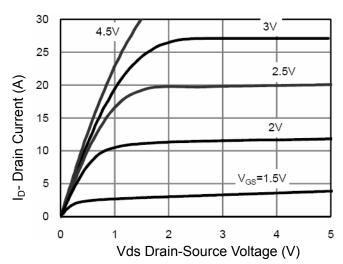
# 1) Gate charge test Circuit:



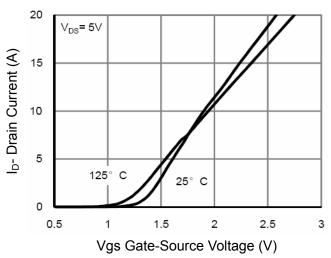
# 2) Switch Time Test Circuit:



# **Typical Electrical and Thermal Characteristics (Curves)**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

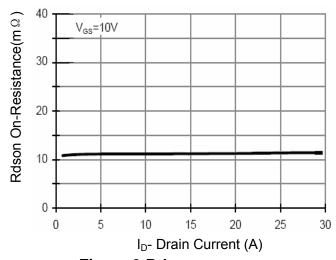
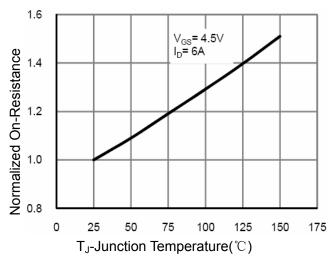


Figure 3 Rdson- Drain Current



**Figure 4 Rdson-Junction Temperature** 

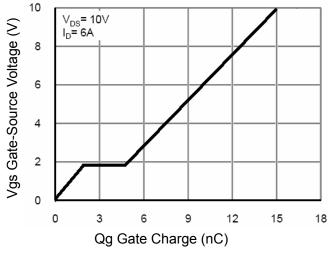


Figure 5 Gate Charge

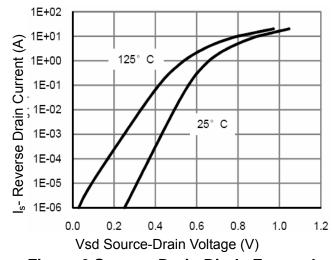


Figure 6 Source- Drain Diode Forward



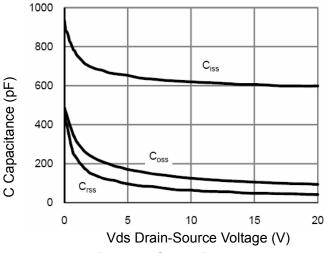


Figure 7 Capacitance vs Vds

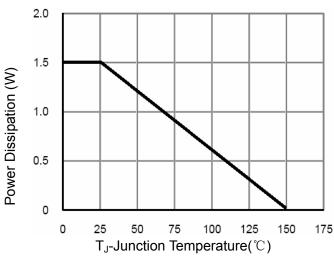


Figure 9 Power De-rating

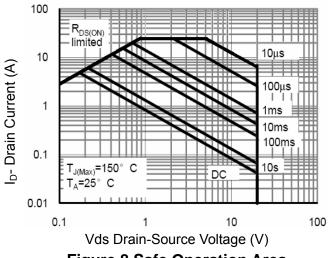


Figure 8 Safe Operation Area

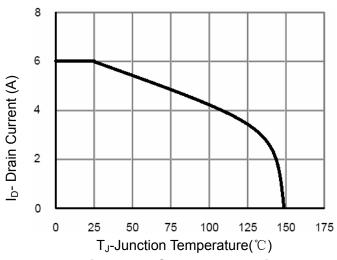
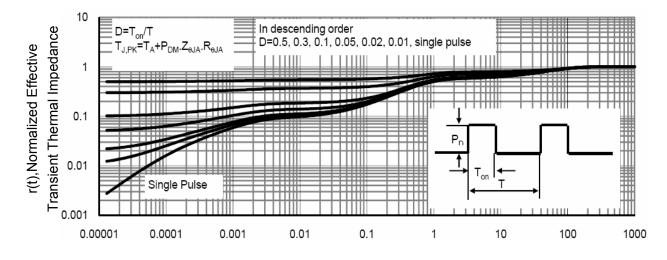


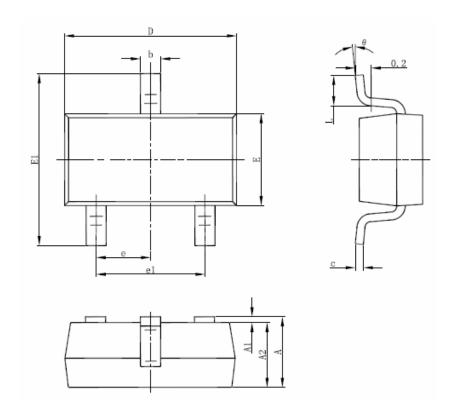
Figure 10 Current De-rating



Square Wave Pluse Duration(sec)

**Figure 11 Normalized Maximum Transient Thermal Impedance** 

# **SOT-23-3L Package Information**



| Symbol | Dimensions Ir | Millimeters | Dimensions | In Inches |
|--------|---------------|-------------|------------|-----------|
| Symbol | Min           | Max         | Min        | Max       |
| Α      | 1.050         | 1.250       | 0.041      | 0.049     |
| A1     | 0.000         | 0.100       | 0.000      | 0.004     |
| A2     | 1.050         | 1.150       | 0.041      | 0.045     |
| b      | 0.300         | 0.500       | 0.012      | 0.020     |
| С      | 0.100         | 0.200       | 0.004      | 0.008     |
| D      | 2.820         | 3.020       | 0.111      | 0.119     |
| E      | 1.500         | 1.700       | 0.059      | 0.067     |
| E1     | 2.650         | 2.950       | 0.104      | 0.116     |
| е      | 0.950         | (BSC)       | 0.037(     | BSC)      |
| e1     | 1.800         | 2.000       | 0.071      | 0.079     |
| L      | 0.300         | 0.600       | 0.012      | 0.024     |
| θ      | 0°            | 8°          | 0°         | 8°        |

## **Notes**

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact

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